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Inventor : CHEN, WEN-CHING

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REVOCATION OF POWER OF ATTORNEY AND
APPOINTMENT OF POWER OF ATTORNEY

The owner of the above-identified U.S. Patent, hereby revokes all Powers of Attorney previously given and hereby appoints the following Attorneys to transact all business in the U.S. Patent and Trademark Office connected therewith:

Morton J. Rosenberg, Esq., Reg. #26,049
David I. Klein, Esq., Reg. #33,253
Jun Y. Lee, Esq., Reg. #40,262
Rosenberg, Klein & Lee
3458 Ellicott Center Drive-Suite 101
Ellicott City, Maryland 21043

Send all correspondence to:

Rosenberg, Klein & Lee
3458 Ellicott Center Drive-Suite 101
Ellicott City, Maryland 21043

Please direct all telephone calls to:

(410) 465-6678

Respectfully submitted,

JUL 05 2004

Date

CHEN, WEN-CHING
CHEN, WEN-CHING